



**Chips**\*\*\*  
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**LEEC** **S** **2024**  
**GHENT** BELGIUM  
5-6 December

**Lab-to-Fab Accelerators under  
the Chips for Europe Initiative**

Elisabeth Steimetz  
EPoSS Director

# Chips Act Pillar 1: Chips for Europe Initiative

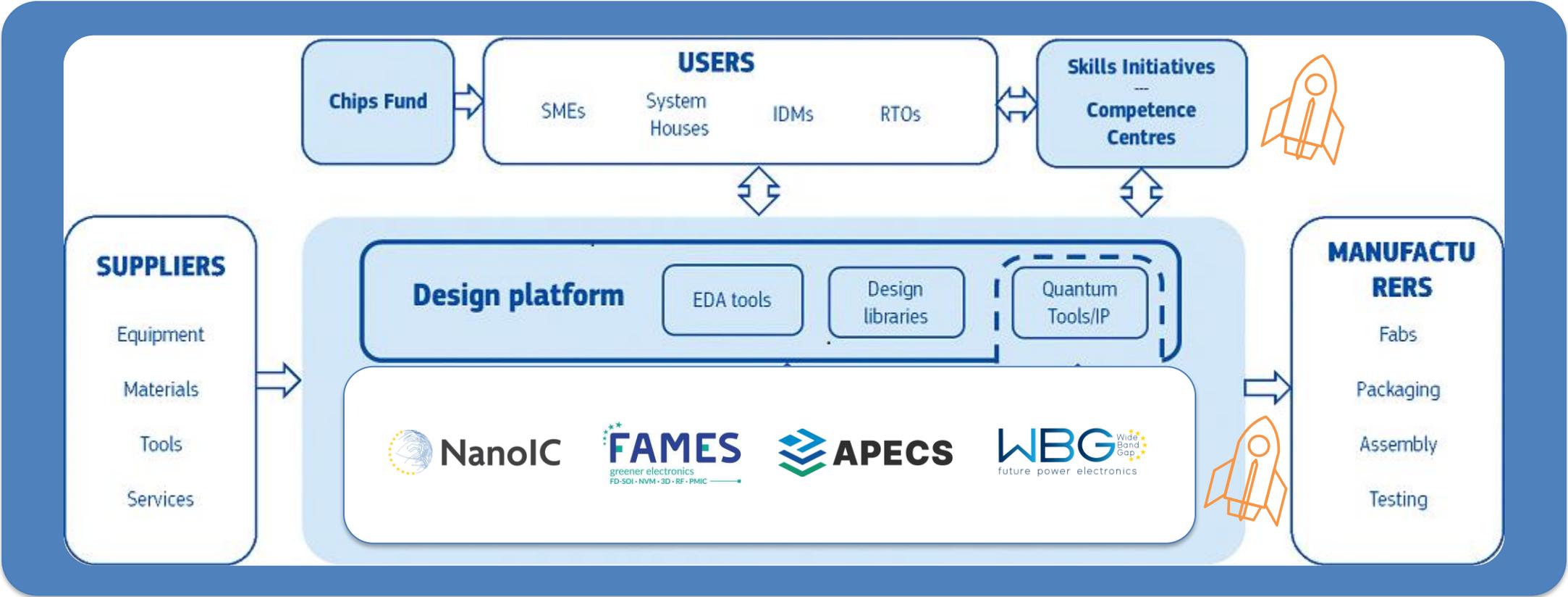
Press Release European Commission, Brussels, 30 November 2023

“The first pillar - the Chips for Europe Initiative - reinforces Europe's technological leadership, by facilitating the transfer of knowledge from the lab to the fab, bridging the gap between research and innovation and industrial activities and by promoting the industrialisation of innovative technologies by European businesses.”

EU Chips Act Pillar 1

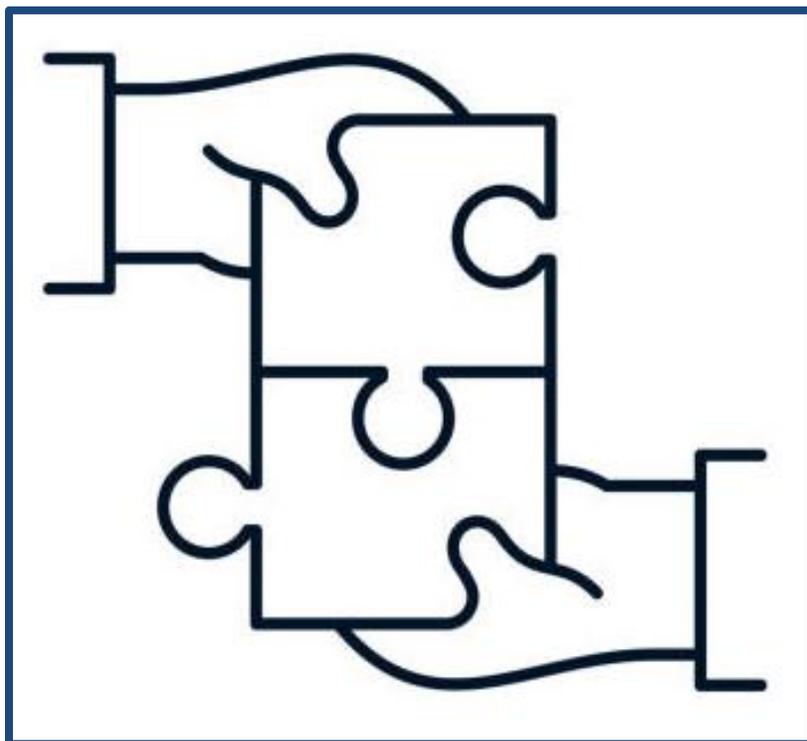
# Chips 4 Europe Initiative: Investments

## Step 1: Capacity building



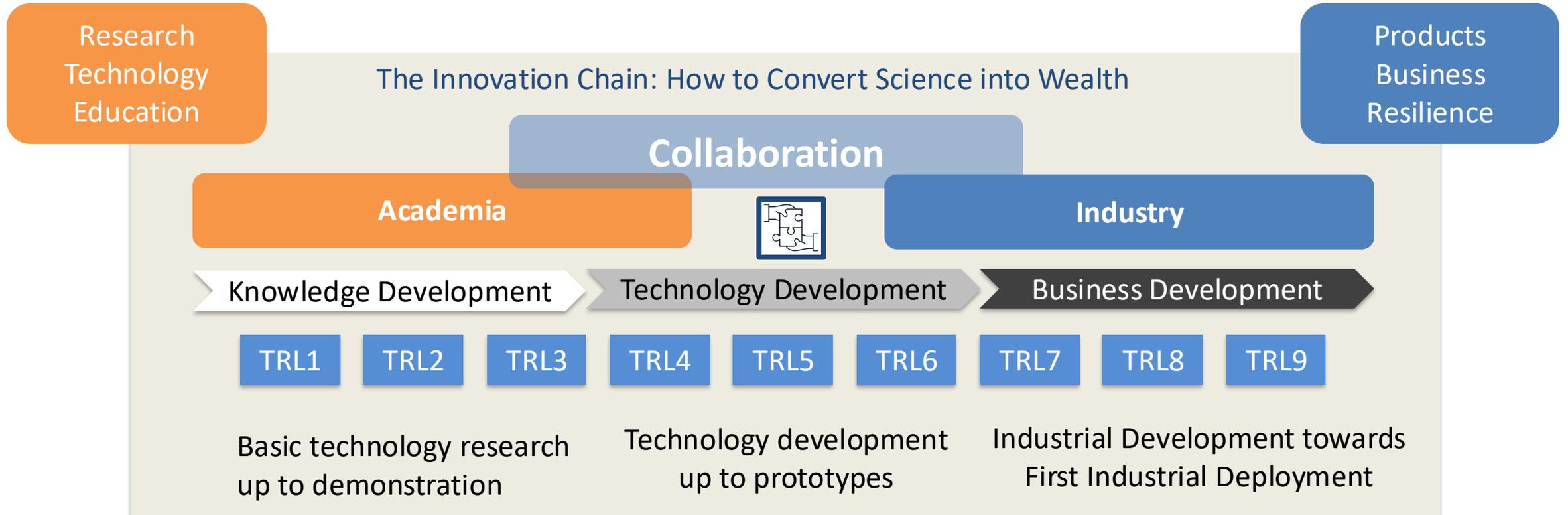
# Chips 4 Europe Initiative: Investments

Step 2: Lab-to-Fab accelerator R&D programme to accelerate technology transfer



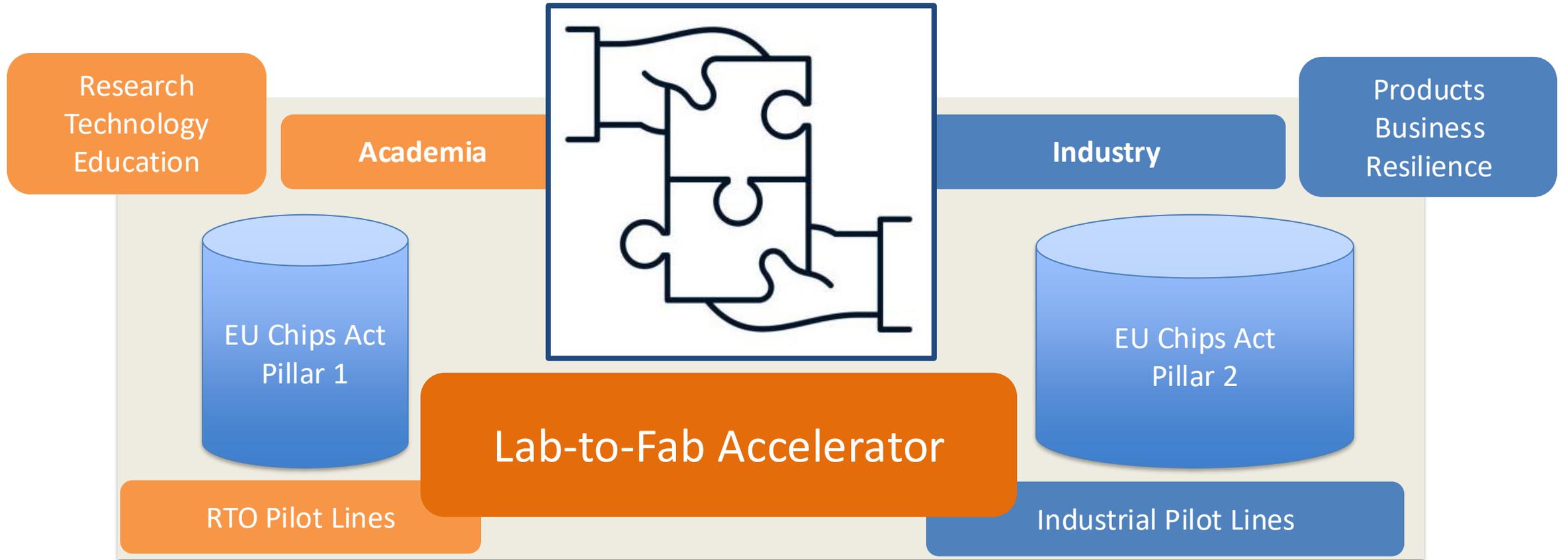
Ensure competitiveness and foster resilience of European semiconductor industry

# Collaboration between RTOs and Industry



Source: [uk-cpi.com](http://uk-cpi.com)

# Role of Lab-to-Fab Accelerators



# Final Recommendations of Pack4EU



**RECOMMENDATIONS**  
for the Implementation  
of Advanced Packaging  
capabilities in Europe



@Pack4EU  
www.pack4eu.eu

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Funded by  
the European Union

**PACK4EU**

**1**  
Implementation of an **Industrial Transfer Instrument** for semiconductor packaging bridging the gap between prototyping and production.

**2**  
Establish a **High-Level Packaging Board** composed of industry leaders to guide strategic directions driven by market needs, ensuring innovation in packaging standards and practices.

**3**  
Implementation of a technical expert group for developing and updating a **Roadmap for Advanced Packaging** in Europe.

**4**  
Creation of **Open Piloting Facilities** for small and medium volume production as a seed for growing European Advanced Packaging capabilities.

**5**  
Development of tools and methodologies for a **Design-to-X approach** & Standardisation for an OPEN European Co-Design Ecosystem.

**6**  
Consolidate international relationships through open calls on **Sustainable Packaging Materials and Substrates**.

**7**  
**A strategy for training and skills development** including: Bridging research and education and facilitating international exchange on training through an EU Education Hub and Building a framework for access to EU-funded research pilot lines for students.

**8**  
Support for **Small and Medium Enterprises** through dedicated open calls applying cascade funding schemes.

**9**  
Creation of a **Pan-European Network** for Advanced Packaging to federate and strengthen the European ecosystem.

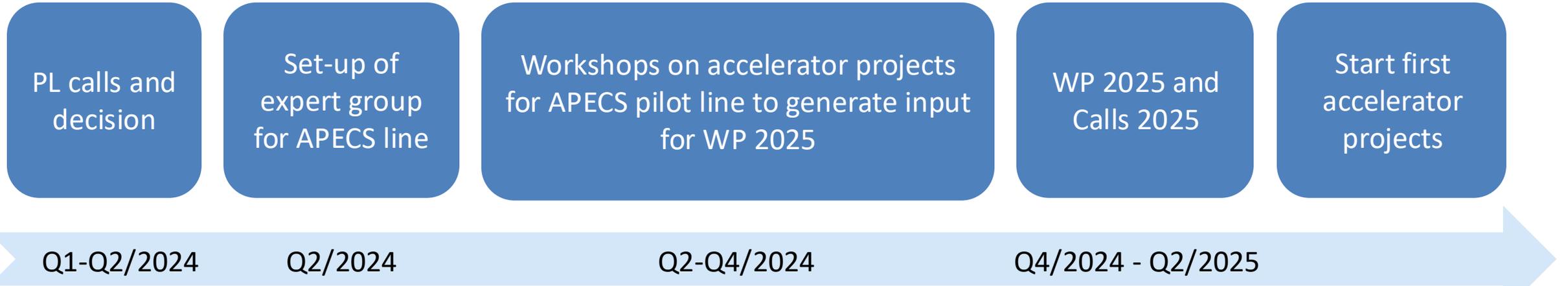
Final Report on Policy Recommendations available online.

# Lab-to-Fab Accelerators: Key principles

How to bring **research into products** faster in Europe?

1. Closer cooperation **between Chips Pilot Lines** and **industrial consortia** from the outset – in line with **industries' roadmaps** to achieve **“right first time”**
2. Joint **standardisation activities** & creation of **platform-based families of the solutions** that can be transferred into different applications, e.g. automotive, industry, health, telecommunications – **scalable and upgradeable for next generation!**
3. Common development of **equipment, materials, processes** and **tools** for rapid testing – with **final cost targets in mind!**
4. **Digital Twins** using AI/ML-based models and standardised tools

# Towards a first Lab-to-Fab Accelerator programme for Advanced Packaging



PL calls and decision

Set-up of expert group for APECS line

Workshops on accelerator projects for APECS pilot line to generate input for WP 2025

WP 2025 and Calls 2025

Start first accelerator projects

Q1-Q2/2024

Q2/2024

Q2-Q4/2024

Q4/2024 - Q2/2025

1. WS with APECS PL

Session on Lab-to-Fab accelerators at SSI 2024 in Hamburg

Expert group installed

Open online expert Workshop

Sep –Nov WP 2025 preparation

February 2025:  
Potential first Call open

# See you!

Today, 17:30 @ Bauwens room 1, floor 2

## Workshop on Lab-to-Fab Accelerator on Advanced Packaging



moderated by Elisabeth Steimetz  
and Steffen Kröhnert



### Speakers

**Antonio Mesquida Küsters**  
Tech-Dilligence



**Eric Fribourg-Blanc**  
Chips JU



**Przemyslaw Jakub Gromala**  
Bosch





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**Thank you very much!**

[Elisabeth.Steimetz@vdivde-it.de](mailto:Elisabeth.Steimetz@vdivde-it.de)

05 December 2024